

### **AMENDMENTS TO THE CLAIMS**

The following Listing of Claims will replace all prior versions, and listing of claims in the Application:

#### **Listing of Claims:**

1. (Amended) A chip adhesive adhered to a stacked packaging structure between two adjacent chips to be displaced each from the other by a selective one of a plurality of distances, and the said chip adhesive including ~~includes~~ a plurality of stuff particles contained therein said stuff particles having a selective dimensional length dependent on one of said selective distances between said adjacent chips to ~~keep~~ maintain the chip adhesive to ~~with~~ a predetermined thickness.
2. (Original) The chip adhesive of claim 1 can further control the thickness through suitably selecting a type of the stuff particle.
3. (Original) The chip adhesive of claim 1 can further control the thickness through suitably selecting a quantity of the stuff particle.
4. (Canceled)
5. (Canceled)

6. (New) The chip adhesive as recited in claim 1 wherein all of said stuff particles being non-spherical in contour.

7. (New) The chip adhesive as recited in claim 6 wherein all of said stuff particles are prolate spheroidal in contour for maximizing an adhesive area of said stuff particles to said surrounding adhesive.